

P-Channel Enhancement-Mode Vertical DMOS FET

Features

- ► Low threshold (-2.0V max.)
- High input impedance
- Low input capacitance
- Fast switching speeds
- Low on-resistance
- Free from secondary breakdown
- Low input and output leakage

Applications

- Logic level interfaces ideal for TTL and CMOS
- Solid state relays
- Battery operated systems
- Photo voltaic drives
- Analog switches
- General purpose line drivers
- Telecom switches

General Description

This low threshold, enhancement-mode (normally-off) transistor utilizes a vertical DMOS structure and Supertex's well-proven, silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Ordering Information

Part Number	Package Option	Packing	
TP2635N3-G	3-Lead TO-92	1000/Bag	
TP2635N3-G P002			
TP2635N3-G P003			
TP2635N3-G P005	3-Lead TO-92	2000/Reel	
TP2635N3-G P013			
TP2635N3-G P014			

⁻G denotes a lead (Pb)-free / RoHS compliant package.

Devices in Wafer / Die form are lead (Pb)-free / RoHS compliant.

Product Summary

BV _{DSS} /BV _{DGS}	R _{DS(ON)} (max)	l _{D(ON)} (min)	V _{GS(th)} (max)
-350V	15Ω	-2.0A	-0.7V

Pin Configuration



Absolute Maximum Ratings

Parameter	Value
Drain-to-source voltage	BV _{DSS}
Drain-to-gate voltage	BV _{DGS}
Gate-to-source voltage	±20V
Operating and storage temperature	-55°C to +150°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

Product Marking



Package may or may not include the following marks: Si or 🎧

the following marks: Si or **﴿** TO-92

Typical Thermal Resistance

Package	$oldsymbol{ heta}_{ja}$
TO-92	132°C/W

Contact factory for Wafer / Die availablity.

Thermal Characteristics

Package	l _D (continuous) [†]	I _D (pulsed)	Power Dissipation @T _A = 25°C	l _{DR} †	l _{DRM}
TO-92	-180mA	-800mA	1.0W	-180mA	-800mA

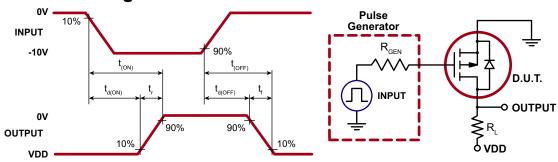
Notes:

Electrical Characteristics (T_A = 25°C unless otherwise specified)

Sym	Parameter	Min	Тур	Max	Units	Conditions	
BV _{DSS}	Drain-to-source breakdown voltage	-350	-	-	V	$V_{GS} = 0V, I_{D} = -2.0mA$	
V _{GS(th)}	Gate threshold voltage	-0.8	-	-2.0	V	$V_{GS} = V_{DS}$, $I_D = -1.0$ mA	
$\Delta V_{GS(th)}$	Change in V _{GS(th)} with temperature	-	-	5	mV/°C	$V_{GS} = V_{DS}$, $I_D = -1.0$ mA	
I _{GSS}	Gate body leakage	-		-100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
			-	-1.0	μA	$V_{GS} = 0V, V_{DS} = -100V$	
I _{DSS}	Zero gate voltage drain current	_		-10.0		$V_{GS} = 0V$, $V_{DS} = Max rating$	
D55				-1.0	mA	V_{DS} = 0.8 Max Rating, V_{GS} = 0V, T_{A} = 125°C	
I _{D(ON)}	On-state drain current	-0.7	-	-	Α	$V_{GS} = -10V, V_{DS} = -25V$	
	Static drain-to-source on-state resistance	-	12	15	Ω	$V_{GS} = -2.5V, I_{D} = -20mA$	
R _{DS(ON)}			11	15		$V_{GS} = -4.5V, I_{D} = -150mA$	
			11	15		$V_{GS} = -10V, I_{D} = -300mA$	
$\Delta R_{DS(ON)}$	Change in R _{DS(ON)} with temperature	-	-	0.75	%/°C	$V_{GS} = -10V, I_{D} = -300mA$	
G_{FS}	Forward transconductance	200	-	-	mmho	$V_{DS} = -25V, I_{D} = -300mA$	
C _{ISS}	Input capacitance	-	_	300		V _{GS} = 0V,	
C _{oss}	Common source output capacitance	-	_	50	pF	$V_{DS} = -25V,$ f = 1.0MHz	
C _{RSS}	Reverse transfer capacitance	-	-	12			
t _{d(ON)}	Turn-on delay time	-	-	10		V _{DD} = -25V,	
t,	Rise time	-	_	15			
t _{d(OFF)}	Turn-off delay time	-	-	60	ns	$I_D = -300 \text{mA},$ $R_{GEN} = 25\Omega$	
t _f	Fall time	-	-	40		GEN	
V _{SD}	Diode forward voltage drop	-		-1.8	V	V _{GS} = 0V, I _{SD} = -200mA	
t _{rr}	Reverse recovery time	-	300	-	ns	V _{GS} = 0V, I _{SD} = -200mA	

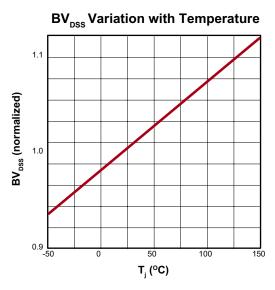
- All D.C. parameters 100% tested at 25C unless otherwise stated. (Pulse test: 300s pulse, 2% duty cycle.)
 All A.C. parameters sample tested.

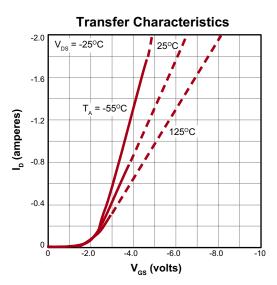
N- Channel Switching Waveforms and Test Circuit

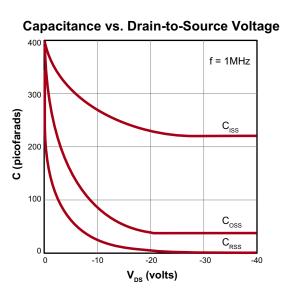


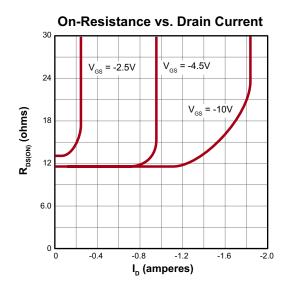
 $[\]dagger I_D$ (continuous) is limited by max rated T_i .

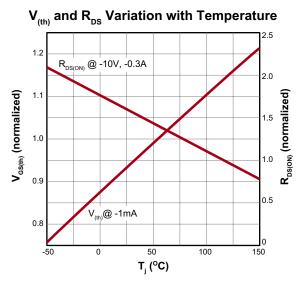
Typical Performance Curves

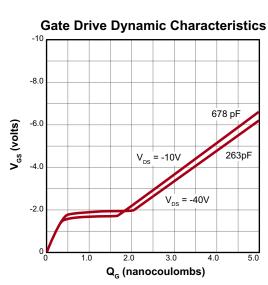




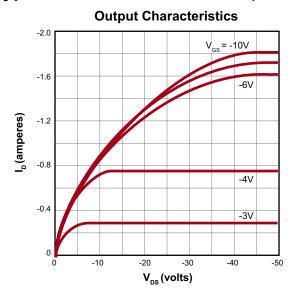


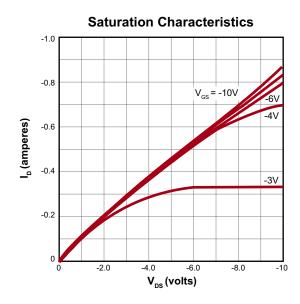


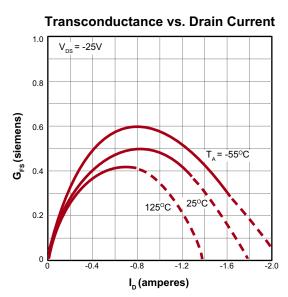


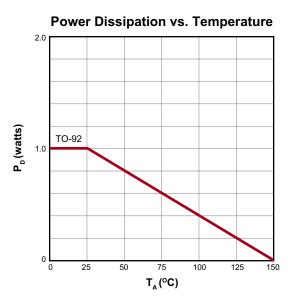


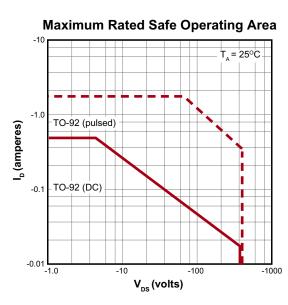
Typical Performance Curves (cont.)

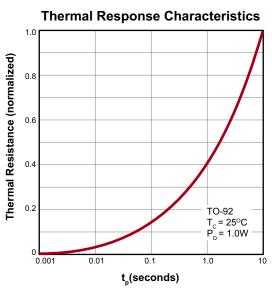




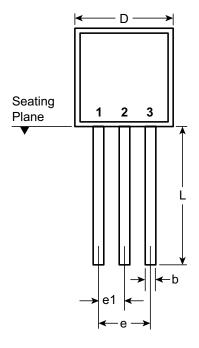


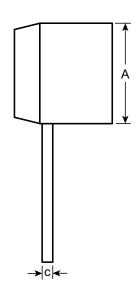






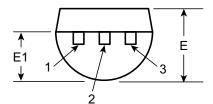
3-Lead TO-92 Package Outline (N3)





Front View

Side View



Symb	ol	Α	b	С	D	E	E1	е	e1	L
Dimensions (inches)	MIN	.170	.014 [†]	.014 [†]	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022 [†]	.022 [†]	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

Drawings not to scale.

Supertex Doc.#: DSPD-3TO92N3, Version E041009.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to http://www.supertex.com/packaging.html.)

Supertex inc. does not recommend the use of its products in life support applications, and will not knowingly sell them for use in such applications unless it receives an adequate "product liability indemnification insurance agreement." **Supertex inc.** does not assume responsibility for use of devices described, and limits its liability to the replacement of the devices determined defective due to workmanship. No responsibility is assumed for possible omissions and inaccuracies. Circuitry and specifications are subject to change without notice. For the latest product specifications refer to the **Supertex inc.** (website: http://www.supertex.com)

©2013 **Supertex inc.** All rights reserved. Unauthorized use or reproduction is prohibited.

Supertex inc.

^{*} This dimension is not specified in the JEDEC drawing.

[†] This dimension differs from the JEDEC drawing.